

CLAIMS PRESENTED

1-21. Cancelled

22. (Newly Presented) An apparatus comprising:
a device chip including circuit elements fabricated on a substrate;
a cap covering at least a portion of said device chip; and
gasket with treaded surface sealing said cap to said device chip.

23. (Newly Presented) The apparatus recited in claim 22 wherein said treaded surface includes tread cavities.

24. (Newly Presented) The apparatus recited in claim 22 wherein said device chip includes adhesive on which said gasket is attached.

25. (Newly Presented) The apparatus recited in claim 22 wherein said cap is cold-weld bonded onto said device chip.

26. (Newly Presented) The apparatus recited in claim 25 wherein gold is used as cold-welded metal.

27. (Newly Presented) The apparatus recited in claim 22 wherein said cap hermetically seals said circuit elements.

28. (Newly Presented) The apparatus recited in claim 22 wherein said gasket having a width in a range of four to 30 microns.

29. (Newly Presented) The apparatus recited in claim 22 wherein said gasket having a thickness in a range of five to 50 microns.

30. (Newly Presented) The apparatus recited in claim 22 wherein said tread having a width in a range of one to five microns.

31. (Newly Presented) The apparatus recited in claim 22 wherein said tread defines tread cavities, each tread cavity having a width ranging from one to five microns.

32. (Newly Presented) The apparatus recited in claim 22 wherein said tread defines tread cavities, each tread cavity having a depth in a range of one to three microns.

33. (Newly Presented) The apparatus recited in claim 22 wherein said tread defines tread cavities, each tread cavity having a length in a range of 10 to 50 microns.

34. (Newly Presented) The apparatus recited in claim 22 wherein said gasket is made from same material as said cap.

35. (Newly Presented) An apparatus comprising:
a device chip including a circuit elements;
a cap and a gasket, said cap covering at least a portion of said device chip; and
said device chip and said gasket having a treaded surface adapted to seal said cap to said device chip.

36. (Newly Presented) The apparatus recited in claim 35 wherein said treaded surface includes tread cavities.

37. (Newly Presented) The apparatus recited in claim 35 further comprising gasket as a seal between said device chip and said gasket.

Respectfully submitted,

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